



Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

IPC-1752-2 v1.02

IPC Web Site for Information on IPC-1752 Standard
<http://www.ipc.org/IPC-175x>

Form Type *

Declaration Class *

Supplier Information

Company Name *	Company Unique ID	Unique ID Authority	Response Date *	Response Document ID					
Contact Name *	Title - Contact	Phone - Contact *	Email - Contact *						
Authorized Representative *	Title - Representative	Phone - Representative *	Email - Representative *		Supplier Comments or URL for Additional Information				
	Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight	UOM	Unit Type
	Alternate Recommendation				Alternate Item Comments				

Manufacturing Process Information

Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	Number of Reflow Cycles
			C	seconds	

Comments

Save the fields in this form to a file

Import fields from a file into this form

Locked

RoHS Material Composition Declaration

Declaration Type *

RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

RoHS Declaration *

Supplier Acceptance

Exemptions: The items on this form meet the specifications of the RoHS Definition above, except for the following application-specific exemptions. Check the appropriate boxes below for the applicable exemptions for the item.

- | | |
|--|--|
| <input type="checkbox"/> 1. Mercury in compact fluorescent lamps not exceeding 5 mg per lamp | <input type="checkbox"/> 7c. Lead in electronic ceramic parts (e.g. piezoelectronic devices) |
| <input type="checkbox"/> 2a. Mercury in straight fluorescent lamps for general purposes not exceeding 10 mg in halophosphate lamps | <input type="checkbox"/> 8. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC amending Directive 76/769/EEC relating to restrictions on the marketing and use of certain dangerous substances |
| <input type="checkbox"/> 2b. Mercury in straight fluorescent lamps for general purposes not exceeding 5 mg in triphosphate lamps with a normal lifetime | <input type="checkbox"/> 9. Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators |
| <input type="checkbox"/> 2c. Mercury in straight fluorescent lamps for general purposes not exceeding 8 mg in triphosphate lamps with long lifetime | <input type="checkbox"/> 10a. DecaBDE in polymeric applications |
| <input type="checkbox"/> 3. Mercury in straight fluorescent lamps for special purposes | <input type="checkbox"/> 10b. Lead in lead-bronze bearing shells and bushes |
| <input type="checkbox"/> 4. Mercury in other lamps not specifically mentioned in this list | <input type="checkbox"/> 11. Lead used in compliant pin connector systems |
| <input type="checkbox"/> 5. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes | <input type="checkbox"/> 12. Lead as a coating material for a thermal conduction module c-ring |
| <input type="checkbox"/> 6a. Lead as an alloying element in steel containing up to 0.35% lead by weight | <input type="checkbox"/> 13a. Lead in optical and filter glass |
| <input type="checkbox"/> 6b. Lead as an alloying element in aluminum containing up to 0.4% lead by weight | <input type="checkbox"/> 13b. Cadmium in optical and filter glass |
| <input type="checkbox"/> 6c. Lead as an alloying element in copper containing up to 4% lead by weight | <input type="checkbox"/> 14. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight |
| <input type="checkbox"/> 7a. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85 % by weight or more lead) | <input type="checkbox"/> 15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages |
| <input type="checkbox"/> 7b. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications | |

Declaration Signature

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

Homogeneous Material Composition Declaration for Electronic Products

Requester Instructions: The requester can optionally include additional substance categories and substances that must be declared for the item on this form. This is in addition to JIG Level A and JIG Level B substances already included for the JIG section. The requester should enter additional substance categories and then enter name of the substance and the CAS number. These entries will be accessible to the supplier via Level drop-down by selecting "Requester". Use the Load "Requester" and Test button to view the entries, just select "Requester" in the Level drop-down list in the previous section.

	Substance Category		Substance	CAS